Compliant with IEC 62474/ D9.00

Міскоснір			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials				J-STD-609A Product Marking and/or Pkg. Labeling e3
Semiconductor Device Type:	T3X	044 QFN 8x8x0.9mm Matte Tin "Contained In"	% Total	1	1			<u> </u>		
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	82.80	(mg) Total	Mold Compound	% ot Total Weight	43.95
Silica, vitreous (or fused)	60676-86-0	Mold Compound	37.358	70.382	373.575		Silica, vitreous (or fused)	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	3.824	7.204	38,237		Epoxy Resin	Trade Secret	8.70	
Phenolic Resin	Trade Secret	Mold Compound	2.637	4.968	26,370		Phenolic Resin	Trade Secret	6.00	
Carbon Black	1333-86-4	Mold Compound	0.132	0.248	1,319		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	47.904	90.251	479,038			Total	100.00	-
Iron	7439-89-6	Lead Frame	1.178	2.220	11,783	94.46	(mg) Total	Lead Frame	% of Total Weight	50.14
Silver	7440-22-4	Lead Frame	0.953	1.795	9,527		Copper	7440-50-8	95.54	
Zinc	7440-66-6	Lead Frame	0.065	0.123	652	1	Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.040	0.076	401	1	Silver	7440-22-4	1.90	
Silver	7440-22-4	Die Attach	1.326	2.499	13,264		Zinc	7440-66-6	0.13	
Octahydro-4,7-methano-1H-indenediyl)bis(methylene) diacrylate	42594-17-2	Die Attach	0.091	0.172	912		Phosphorous	7723-14-0	0.08]
Methacrylic acid, isobornyl ester	7534-94-3	Die Attach Die Attach	0.091	0.172	912			Total	100.00	
Exo-1,7,7-Trimethylbicyclo[2.2.1]hept-2-yl acrylate	5888-33-5		0.091	0.172	912	3.01	(mg) Total	Die Attach	% of Total Weight	1.6
Silicon	7440-21-3	Dual Chip (Die)	2.830	5.332	28,300		Silver	7440-22-4	82.90	
Copper	7440-50-8	Wire Bond Copper palladium coated (CuPdAu)	0.235	0.443	2,350		ethano-1H-indenediyl)bis(m	42594-17-2	5.70	
Palladium	7440-05-3 7440-57-5	Wire Bond Copper palladium coated (CuPdAu) Wire Bond Copper palladium coated (CuPdAu)	0.005	0.009	48		ethacrylic acid, isobornyl es	7534-94-3 5888-33-5	5.70 5.70	
						EX0-1,/,/-	rimethylbicyclo[2.2.1]hept-	3000-33-3		
Gold				7 336	12 /00					
Gold Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.240	2.336	12,400			Total	100.00	
	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour TOTALS:		2.336 188.400	12,400 1,000,000	5.33	Total (mg)	Total Dual Chip (Die)	% of Total Weight	2.83
Tin semiconductor device and its homogenous materials comply w	7440-31-5 0.1884 th EU Directives	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour TOTALS: In graph TOTALS	1.240 100.000	188.400	1,000,000	5.33		Total		2.83
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